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Attorney Docket No. 10829-8404

PATENT**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: VISHNU K. AGARWAL AND
DINESH CHOPRA

APPLICATION NO.: 10/772,541

FILED: FEBRUARY 5, 2004

FOR: **APPARATUSES FOR FORMING A
PLANARIZING PAD FOR
PLANARIZATION OF
MICROELECTRONIC SUBSTRATES**

EXAMINER: YEWEBDAR T.
TADESSE

ART UNIT: 1734

CONF. No: 8900

Proposed Claim Amendment -**For Discussion Purposes Only****Amendment to the Claims:**

75. (Currently Amended) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, the planarizing pad including a pad support material and a planarizing pad material, wherein the apparatus comprising:

a support device configured to support thea pad support material in a selected position;

a vessel for mixing the planarizing pad material; and

a nozzle in fluid communication with the vessel and configured to form the planarizing pad material into discrete texture elements for disposing on the pad support material, wherein the pad support material is elongated in a longitudinal direction, and wherein the nozzle is positioned to spray the discrete texture elements at least partially in the longitudinal direction.

(616) 855 1521

Remarks

The foregoing claim amendments are provided **for discussion purposes only** in a telephone interview scheduled for _____ p.m. Eastern time between the Examiner and the attorney identified below.

Respectfully submitted,
Perkins Coie LLP

Date: _____

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